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Part Number:

0739446001

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[Product Specification PS-73670-9999 \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73944

Application

Backplane

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

Yes

Keying to Mating Part

Yes

Material - Metal

Phosphor Bronze, Stainless Steel

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.138 In

PC Tail Length (mm)

3.50 mm

PCB Locator

Yes

PCB Retention

None

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Pitch - Term. Interface (in)

0.079 In

Pitch - Term. Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

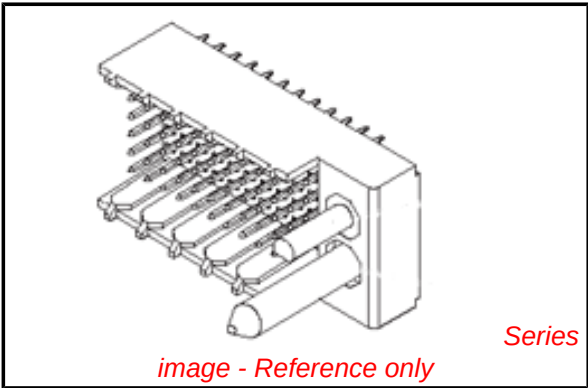
100

Plating min: Termination (µm)

2.5

Polarized to PCB

No



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73944Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane Insertion Signal	0621001400
Contact Tool	
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

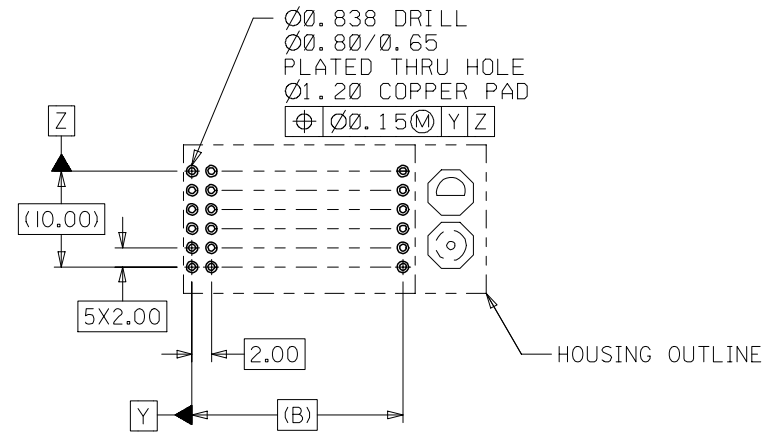
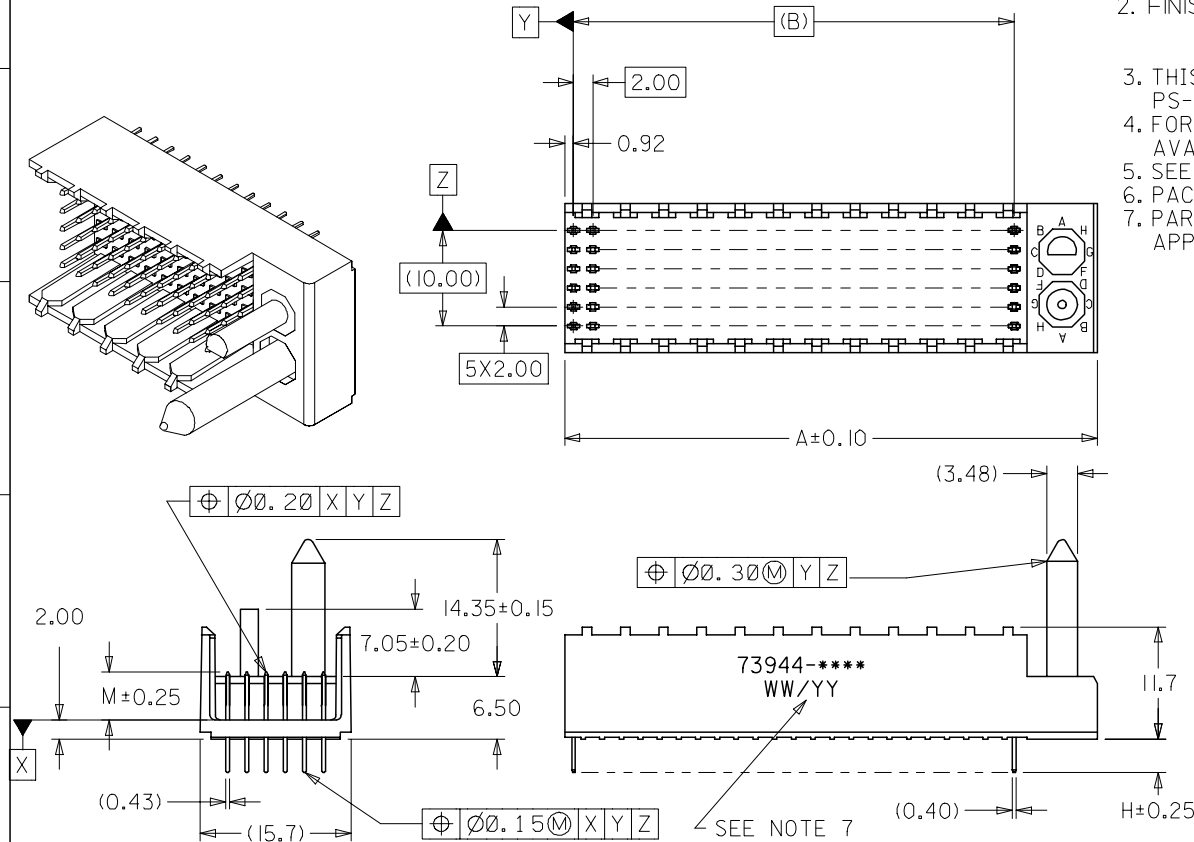
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. SEE SHEET 2 FOR SPECIFIC MATERIAL NUMBERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



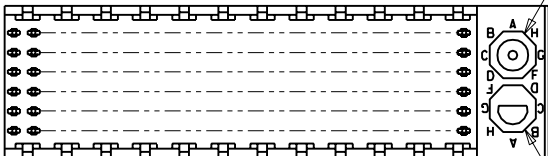
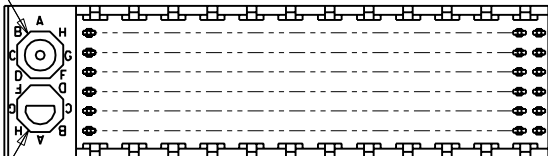
PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRWN:MSI BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
			mmINCH		DRAWN BY JB INGHAM		DATE 1998/01/14	TITLE SALES ASSY HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION				
			4 PLACES ± --- ± ---		CHECKED BY SREED		DATE 1998/01/14					
			3 PLACES ± --- ± ---		APPROVED BY CBIXLER		DATE 1998/01/14					
			2 PLACES ± 0.05 ± ---		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-73944-001		SHEET NO. 1 OF 2			
			1 PLACE ± 0.10 ± ---									
			ANGULAR ±1/2°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

LOCATION A

LOCATION B



REF. MATERIAL NUMBER 73944-1009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73944-1008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

MATERIAL NUMBER ASSIGNMENT

73944- * * * *

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	31.60	22.00	2.00
1	144	55.60	46.00	2.00
2	72	31.60	22.00	2.50
3	144	55.60	46.00	2.50
4	72	31.60	22.00	3.00
5	144	55.60	46.00	3.00
6	72	31.60	22.00	3.50
7	144	55.60	46.00	3.50

NUMBER	DIM "M"
0	5.00
1	5.50
2	6.00

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	
03	A	B
04	B	
05	A	C
06	B	
07	A	D
08	B	
09	A	E
10	B	
11	A	F
12	B	
13	A	G
14	B	
15	A	H
16	B	
17	A	N/A
18	N/A	

SEE SHEET 1
EC No. U81577
DRWN: BINGHAM 98/02/03
CHK: REED 98/02/03
APPR: BIXLER 98/02/03

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
mm INCH
4 PLACES ±0. ±.
3 PLACES ±0. ±.
2 PLACES ±0. N/A ±.
1 PLACE ±0. N/A ±.
ANGULAR: ± 1/2°
DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

SCALE
2 : 1
DESIGN UNITS
mm INCH
DRAWN BY & DATE
JBINGHAM 98/01/14
CHECKED BY & DATE
SREED 98/01/14
APPROVED BY & DATE
CBIXLER 98/01/14
CAD FILENAME
S73944X2.DGN

TITLE: SALES ASSY, HDM BACKPLANE
POLAR/GUIDE OPTION
SOLDER TAIL VERSION
MOLEX INCORPORATED
MATERIAL NO. SEE CHART
DRAWING NO. SD-73944-001
SHEET NO. 2
SIZE B